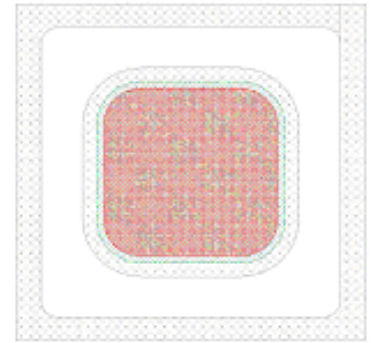
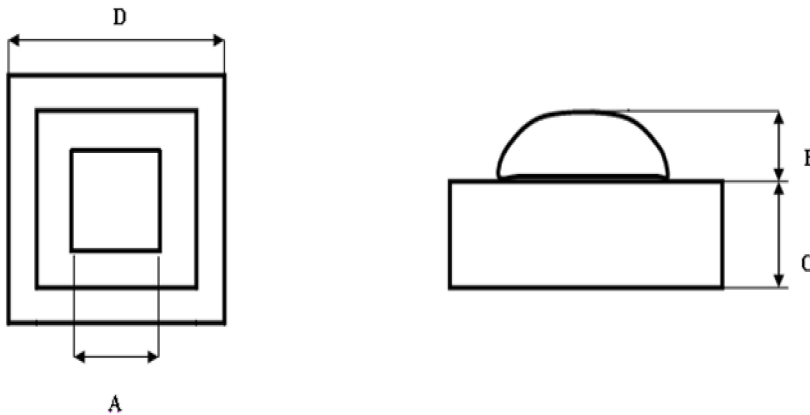


**Description**

Epitaxial Chip  
Suitable for Glass-Tube package  
Chip thickness 140um.  
Top metal: Ag ball, Back metal:Ag  
Wafer size:5", PDPW: 20,000die/Wafer



**Outline**



Parameter	Symbol	Min. Value	Typical Value	Max. Value	Unit
Chip size	D	660		690	uM
chip thickness	C	120		160	uM
Silver ball size	A	460		500	uM
Silver ball height	B	25		60	uM
Street size	/		50		uM

**Maximum ratings**

Parameter	Symbol	Test Condition	Value	Unit
Operating temperature	$T_J$		175	°C
Storage temperature	$T_{STG}$		-50~+175	°C

**Electrical Characteristics (Rating at 25°C ambient, refer to the Finished Goods)**

( $V_F < 1.19V @ I_F = 200mA$ )

Part No.	$V_Z$			Zener impedance			Max.Reverse leakage current		Maximum DC Zener Current $I_{ZM}(mA)$
	$V_{ZNOM}(V)$	$V_{ZT}(V)$	$I_{ZT}(mA)$	$Z_{ZT}(\Omega)@I_{ZT}$	$Z_{ZK}(\Omega)@I_{ZK}$	$I_{ZK}(mA)$	$I_R(\mu A)$	$V_R(V)$	
GDZ2CW071068YQS	6.8	6.42-7.17	73.5	2	700	0.5	5	4.2	266
GDZ2CW071360YQS	36	34.02-37.97	13.9	25	1000	0.25	0.5	27.6	50